

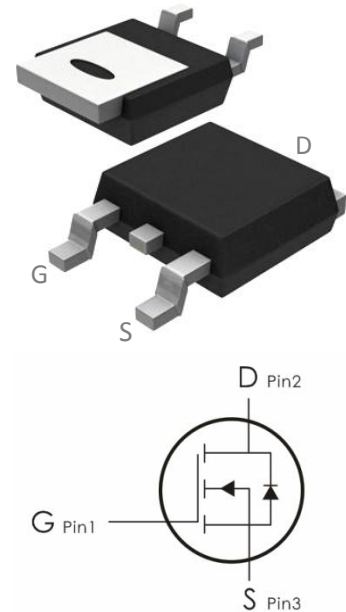
Description:

This N-Channel MOSFET uses advanced trench technology and design to provide excellent $R_{DS(on)}$ with low gate charge.

It can be used in a wide variety of applications.

Features:

- 1) $V_{DS}=650V, I_D=5A, R_{DS(on)} < 2.7 \Omega @ V_{GS}=10V$
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra low $R_{DS(on)}$.
- 5) Excellent package for good heat dissipation.



Absolute Maximum Ratings: ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	650	V
V_{GS}	Gate-Source Voltage	± 30	V
I_D	Continuous Drain Current- $T_C=25^\circ\text{C}$	5	A
	Continuous Drain Current- $T_C=100^\circ\text{C}$	2.5	
I_{DM}	Pulsed Drain Current(Note 1)	25	A
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	80	mJ
I_{AR}	Avalanche Current (Note 1)	5	A
E_{AR}	Repetitive Avalanche Energy (Note 1)	4.5	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	5	V/ns
P_D	Power Dissipation, $T_C=25^\circ\text{C}$	24.5	W
	Power Dissipation-De-rate above 25°C	0.2	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ\text{C}$

Thermal Characteristics:

Symbol	Parameter	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case	5.1	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	45.3	

Package Marking and Ordering Information:

Part NO.	Marking	Package
DO05NG-C	O05N-C	TO-252

Electrical Characteristics: ($T_C=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250 μ A	650	---	---	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{GS} =0V, V _{DS} =650V	---	---	1	μ A
		V _{GS} =0V, V _{DS} =520V, T _c = 125 °C	---	---	10	μ A
I _{GSS}	Gate-Source Leakage Current	V _{GS} =± 30V, V _{DS} =0A	---	---	± 100	nA
On Characteristics						
V _{GS(th)}	GATE-Source Threshold Voltage	V _{GS} =V _{DS} , I _D =250 μ A	2	---	4	V
R _{DS(ON)}	Drain-Source On Resistance	V _{GS} =10V, I _D =2.5A	---	2.3	2.7	Ω
G _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 2 .5A(Note 4)	---	3.8	---	S
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =25V, V _{GS} =0V, f=1MHz	---	400	---	pF
C _{Oss}	Output Capacitance		---	55	---	
C _{rss}	Reverse Transfer Capacitance		---	1.3	---	
Switching Characteristics						
t _{d(on)}	Turn-On Delay Time	V _{DD} =325V, I _D =5A, R _G =25Ω (Note 4,5)	---	7	---	ns
t _r	Rise Time		---	22	---	ns
t _{d(off)}	Turn-Off Delay Time		---	15	---	ns
t _f	Fall Time		---	23	---	ns
Q _g	Total Gate Charge	V _{DS} =520V, V _{GS} =10V, I _D =5A	---	13	---	nC

Q_{gs}	Gate-Source Charge	V _{DS} =520V, V _{GS} =10V, I _D =5A (Note 4,5)	---	4.9	---	nC
Q_{gd}	Gate-Drain Charge		---	2.3	---	nC
Drain-Source Diode Characteristics						
V_{SD}	Source-Drain Diode Forward Voltage	I _S =5A, V _{GS} =0V	---	---	1.2	V
I_S	Continuous Source Current	---	---	---	4	A
I_{SM}	Pulsed Source Current	---	---	---	16	A
T_{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 5 A,	---	378	---	ns
Q_{rr}	Reverse Recovery Charge	dI _F / dt = 100 A/ μ s(Note 4)	---	1.35	---	μ C

Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. L = 40 mH, I_{AS} = 2 A, V_{DD} = 50V, R_G = 25 Ω, Starting T_J = 25°C
3. I_{SD} ≤ 4A, di/dt ≤ 200A/μs, V_{DD} ≤ B_VD_{SS}, Starting T_J = 25°C
4. Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2%
5. Essentially independent of operating temperature

Typical Characteristics: (T_J=25°C unless otherwise noted)

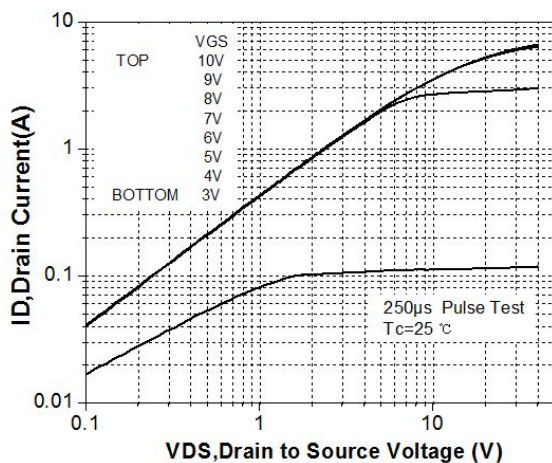


Figure 1. On-Region Characteristics

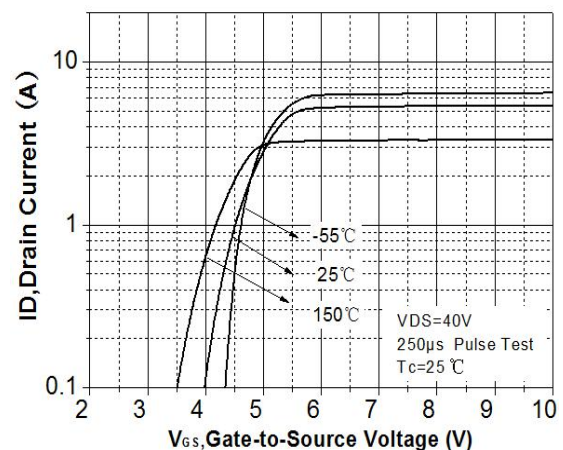


Figure 2. Transfer Characteristics

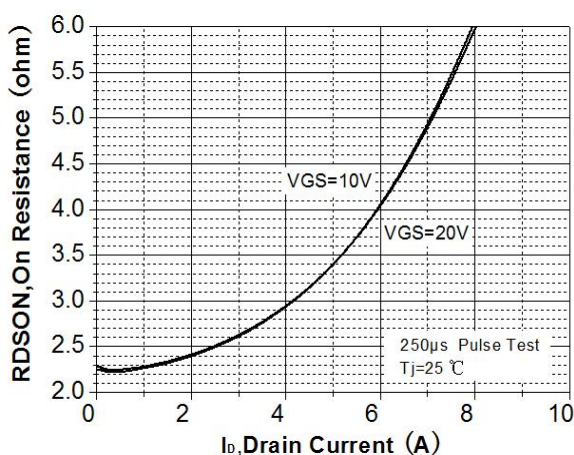


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

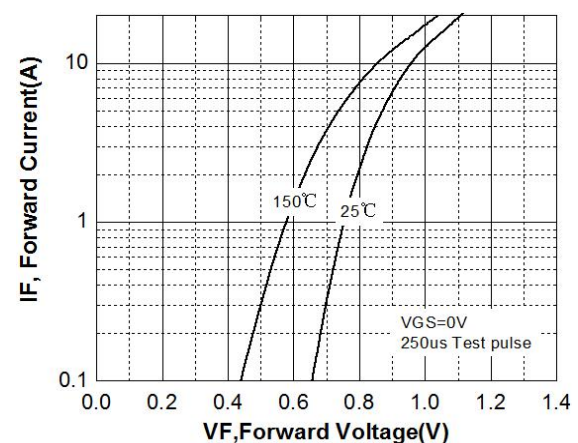


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

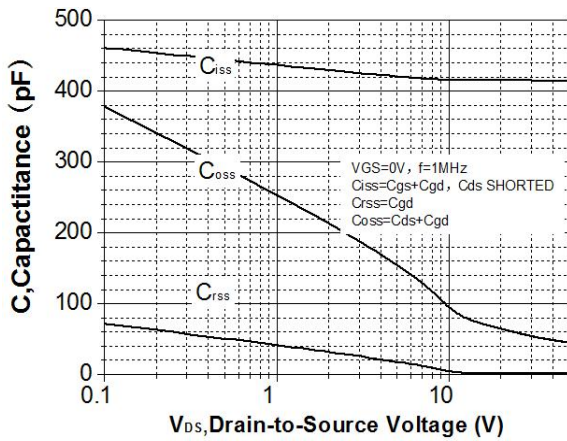


Figure 5 Capacitance Characteristics

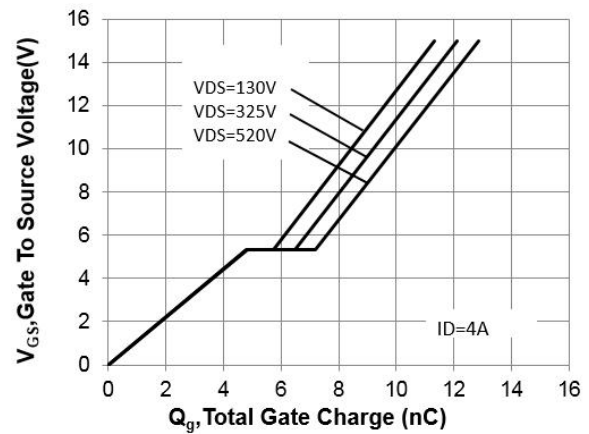


Figure 6. Gate Charge Characteristics

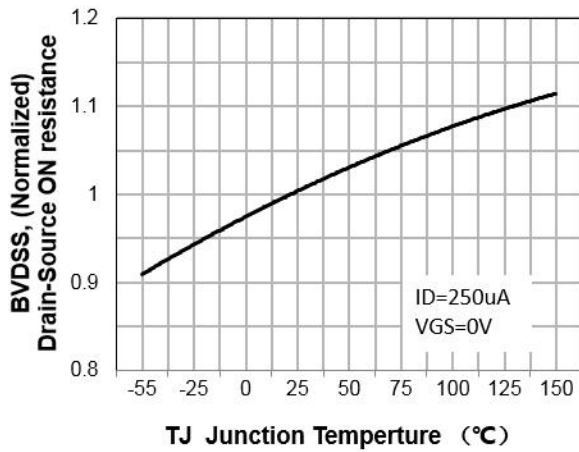


Figure 7. Breakdown Voltage Variation vs Temperature

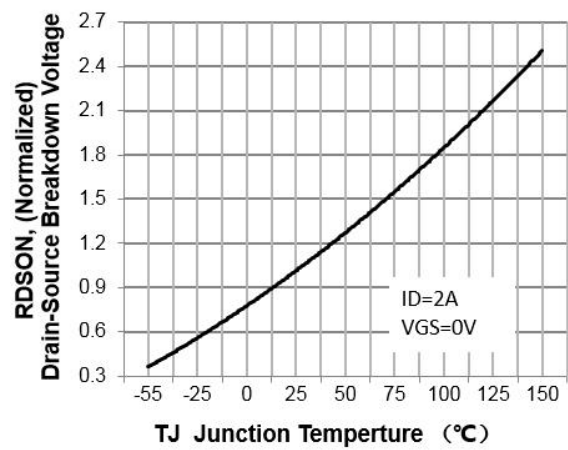


Figure 8. On-Resistance Variation vs Temperature

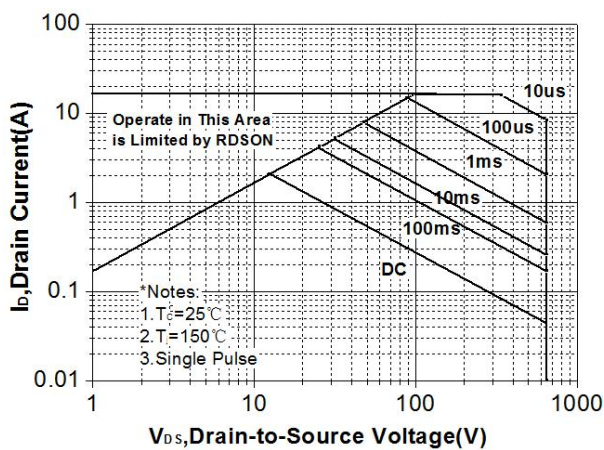


Figure 9. Maximum Safe Operating Area

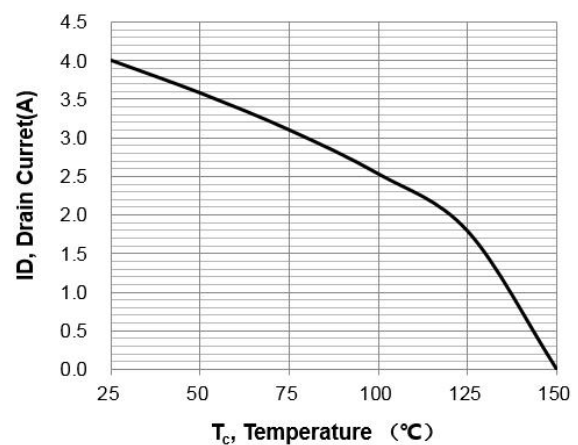


Figure 10. Maximum Drain Current vs Case Temperature

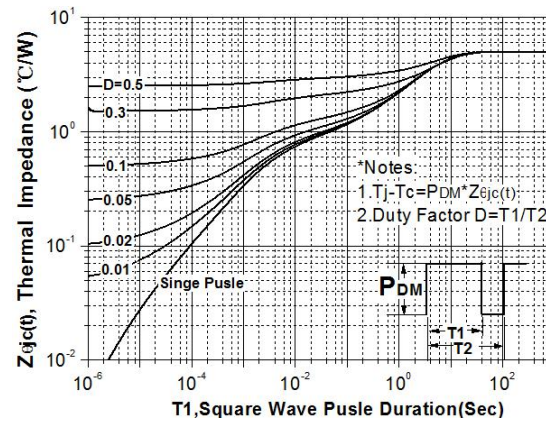


Figure 11. Transient Thermal Response Curve